

IMPACT

TE Internal #: 2007793-1 High Speed Backplane Connectors, 144 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Vertical, IMPACT

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Connector System: Board-to-Board Number of Positions: 144 Row-to-Row Spacing: 1.35 mm [.053 in] Mating Alignment: With

Mating Alignment Type: Keyed

Features



Product Type Features

Signal Arrangement	Differential
Connector System	Board-to-Board
PCB Connector Assembly Type	PCB Mount Header
Shroud Style	Partially Shrouded
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Ground Positions	48
Number of Pairs	48
Stackable	No
Number of Signal Positions	96
Number of Positions	144
Number of Rows	9
Number of Columns	16
PCB Mount Orientation	Vertical

High Speed Backplane Connectors, 144 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Vertical, IMPACT



Impadance100 QOperating Voltage30 VACOperating Voltage30 VACSignal Characteristics20-25 Gb/sNumber of Differential Pairs per Column3Data Rate20-25 Gb/sBody Features100 ColorContact Mating Area LengthBlackPCB Contact Termination Area Plating Material Thickness76-152 µrn(30-60 µn)Contact Mating Area Length1.01 µn(30 µn)Contact TypePinContact Mating Area Plating Material Thickness76 µn(30 µn)Contact Mating Area Plating Material ThicknessGoldContact Mating Area Plating Material ThicknessGoldContact Mating Area Plating Material ThicknessGoldContact Mating Area Plating Material FinishMateriaContact Mating Area Plating Material FinishMateriaContact Mating Area Plating Material FinishMateriaContact Material MaterialGoldContact Material MaterialIninContact Current Rating (Max)Ja Pan(Ja Cance)Contact Current Rating (Max)Ja Karn(JAS ini)Contact Current Rating (Max)Ja Karn(JAS ini)Contact Current Rating (Max)Inrough Hole Press FitTermination Post & Tail LengthInrough Hole Press FitCurlea HardwareWithoutCurlea HardwareWithoutMating RetentionWithoutMaterial ThicknessWithoutContact Current Rating (Max)Inrough Hole Press FitCurrent Rating Material LengthMithoutMaterial ThicknessWit		
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PCB Mount Retention With	Guide Hardware	With
	Mating Retention	Without
	PCB Mount Retention	With
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Mating Alignment With	Mating Alignment	With

High Speed Backplane Connectors, 144 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Vertical, IMPACT



Mating Alignment Type	Keyed
Connector Mounting Type	Board Mount
Housing Features	
Number of Shrouded Sides	2
End Wall Location	Open
Housing Material	LCP - GF (Liquid Crystal Polymer)
Centerline (Pitch)	1.9 mm[.075 in]
Dimensions	
Connector Length	36.9 mm[1.453 in]
Connector Height	24.6 mm[.969 in]
Connector Width	16.7 mm[.657 in]
PCB Thickness (Recommended)	1 mm
PCB Hole Diameter	.36 mm[.014 in]
Row-to-Row Spacing	1.35 mm[.053 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Approved Standards	CSA Certified, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Box & Tube, Tube
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2021 (211)

High Speed Backplane Connectors, 144 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Vertical, IMPACT



Does not contain REACH SVHC

Not Yet Reviewed for halogen content

Halogen Content

Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



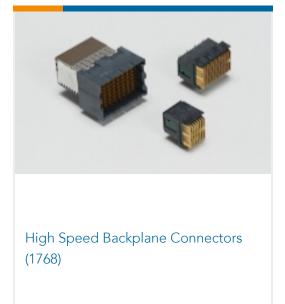
TE Part # 2007711-1 IMP100S,R,RA3P16C,UG,39



TOOL, SEAT 3 PR 16 COL, BP CONN



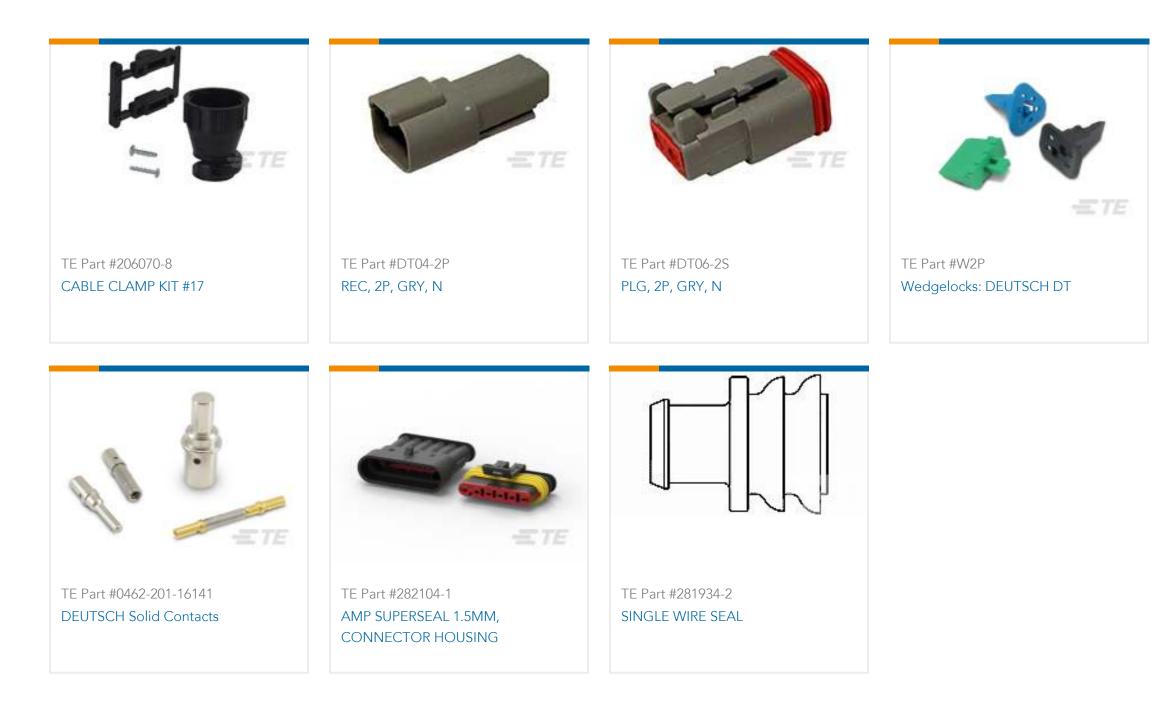
Also in the Series | IMPACT



Customers Also Bought

High Speed Backplane Connectors, 144 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Vertical, IMPACT





Documents

CAD Files

Customer View Model

ENG_CVM_CVM_2007793-1_B.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2007793-1_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2007793-1_B.3d_stp.zip

English

By downloading the CAD file I accept and agree to the $\ensuremath{\text{Terms}}$ and $\ensuremath{\text{Conditions}}$ of use.

Datasheets & Catalog Pages 7-1773458-1_IMPACT_BACKPLANE_CONNECTOR_SYSTEM_CATALOG

English

Product Specifications

Application Specification

English

Agency Approvals Agency Approval Document

English